

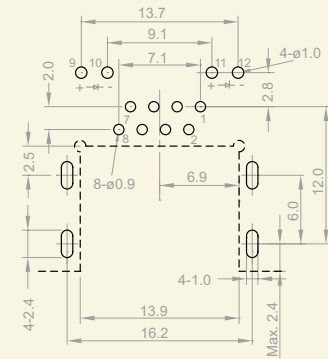
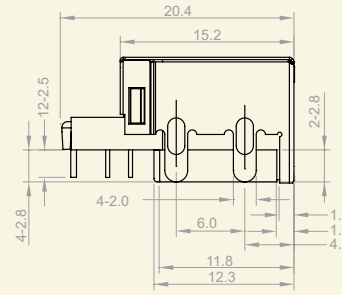
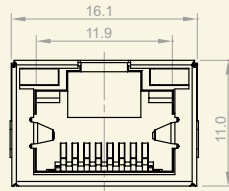
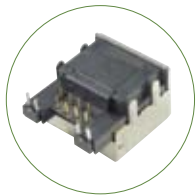
MODULE JACK

MJ3XX Series



76

MJ302A-8000-21D



PCB LAYOUT

NOTE

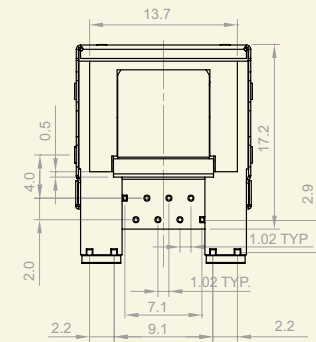
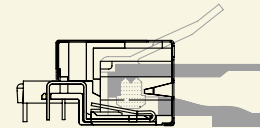
1. MATERIALS

- HOUSING: THERMOPLASTIC.(LCP)
- UL94V-0 COLOR:BLACK
- CONTACTS: PHOSPHOR BRONZE
- SHELL: SUS301-H

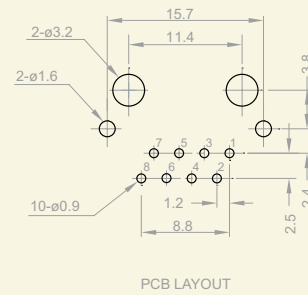
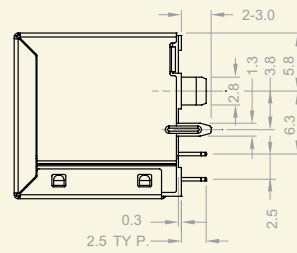
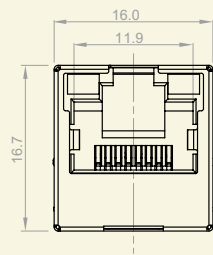
FINISH

2. CONTACT

- 15µ*MIN. GOLD PLATING ON CONTACT AREA.
- 100µ*MIN. TIN PLATING ON SOLDER TAILS.
- 50µ*MIN. NICKEL UNDERPLATING OVERALL.
- SHELL: 50µ*MIN. NICKEL UNDERPLATING OVERALL.
- 3. RECOMMENDED PCB THICKNESS: 1.2mm
- 4. REFLOW SOLDER CAPABLE TO 260°C

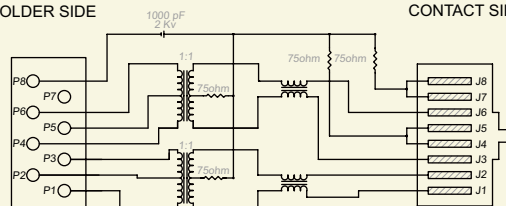


MJ303A-8000-21D



CONNECTOR
SOLDER SIDE

RJ45
CONTACT SIDE



NOTE: 1.0 PINS WITHOUT ELECTRICAL CONNECTION ARE OMITTED
CONNECTOR SCHEMATIC

MATERIAL

HOUSING-LCP

HEAT DEFLECTION TEMP.265
STANDARD COLOR-BLACK
STANDARD COLOR-BLACK
WITH HARD GOLD AND TIN IN SOLDER AREA.
SHIELD-0.25mm THICK COPPER ALLOY.
PLATED WITH NICKEL.